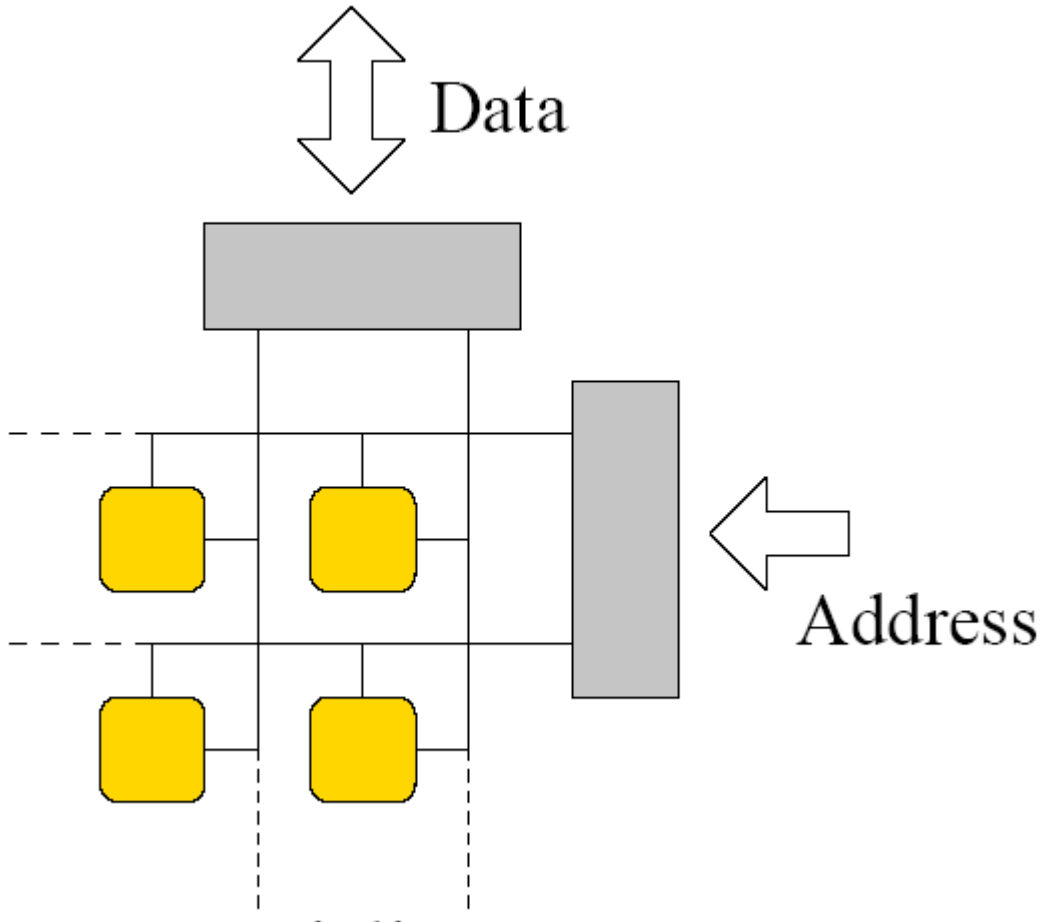


# Semiconductor Memory

## LECTURE 23

- memory organization
- memory-density trends
- flash memory
- DRAM

# Memory organization



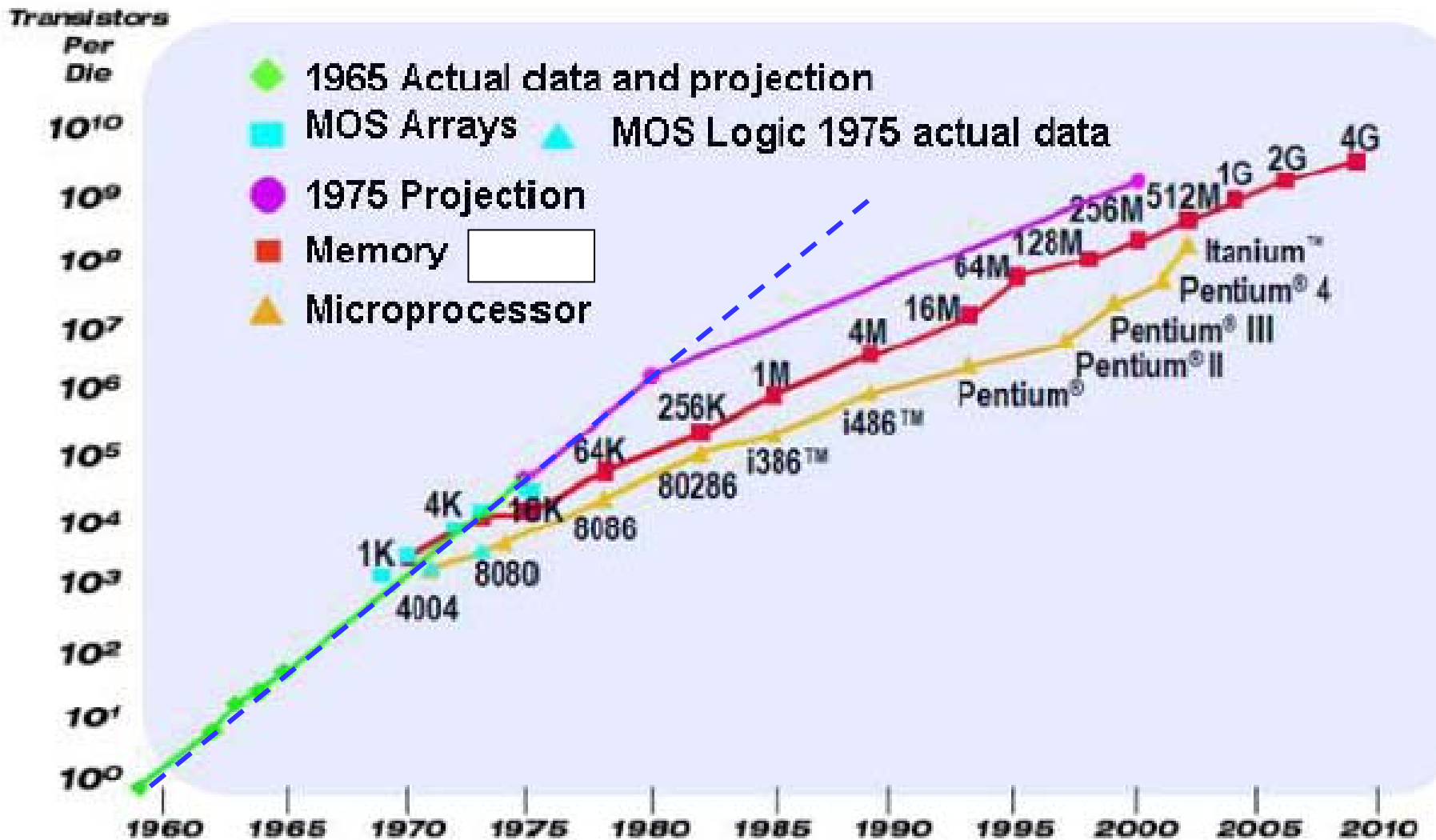
Identify:

- Memory cells
- Word lines
- Bit lines
- Decoder
- MUX/DEMUX

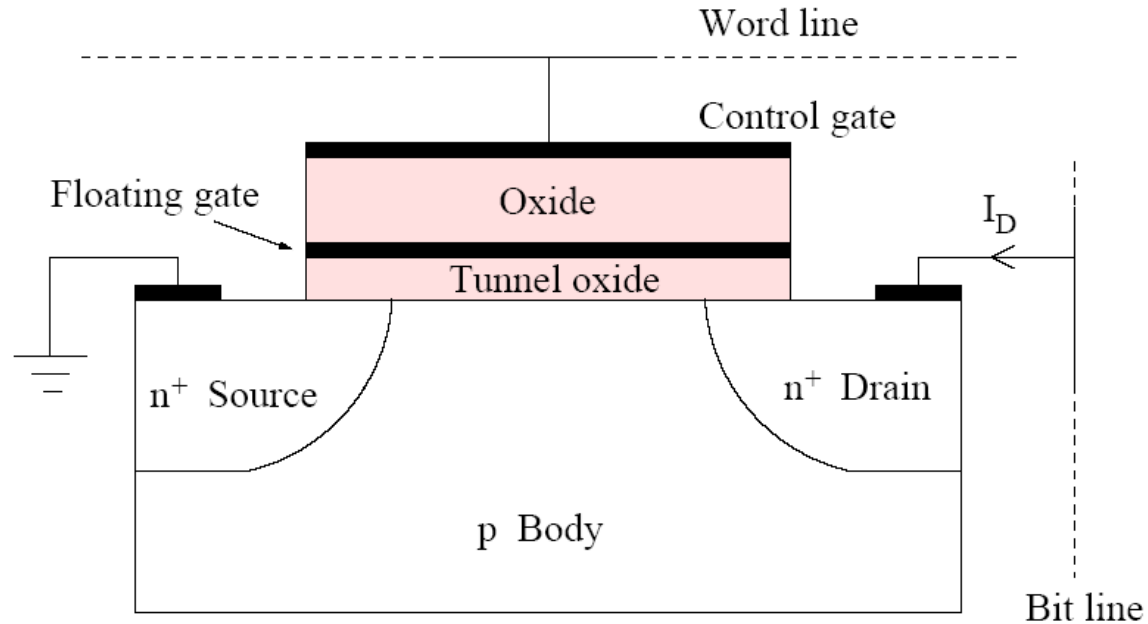
Industry strives to make cells as  as possible.

Sketch a MOST memory cell, showing word- and bit-line connections

# Memory Density



# Flash memory cell

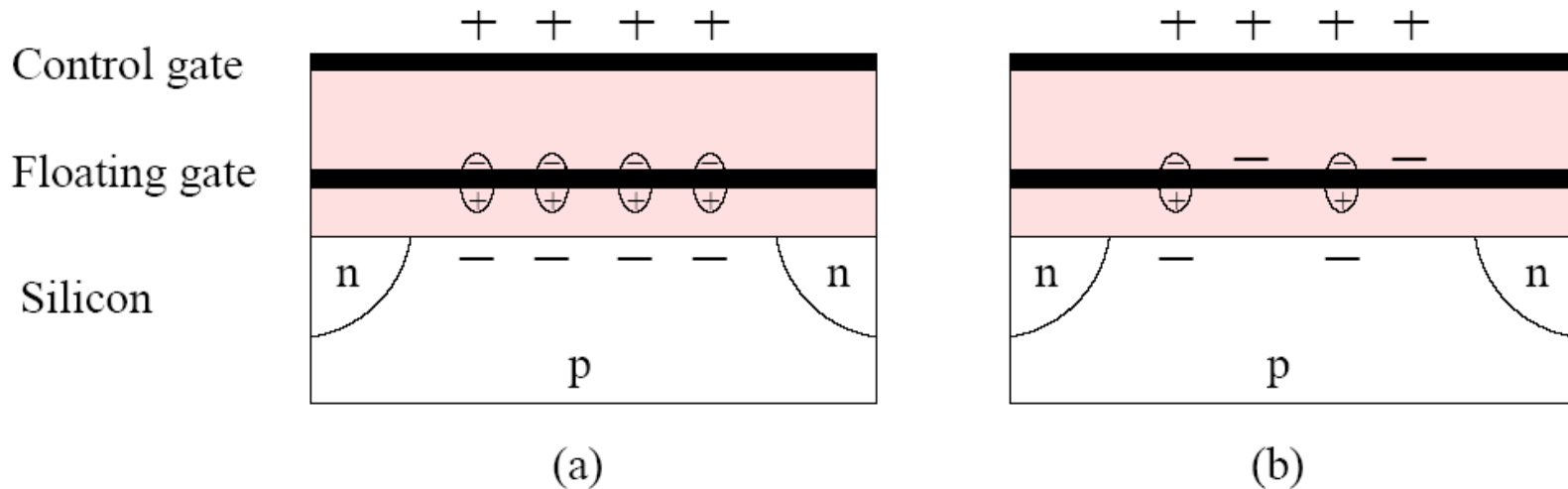


What is the most significant difference from a regular MOSFET?

How is the cell programmed (written and erased)?

How is the cell read?

# Charge on Floating Gate



Let  $Q_n = -4q$  represent inversion.

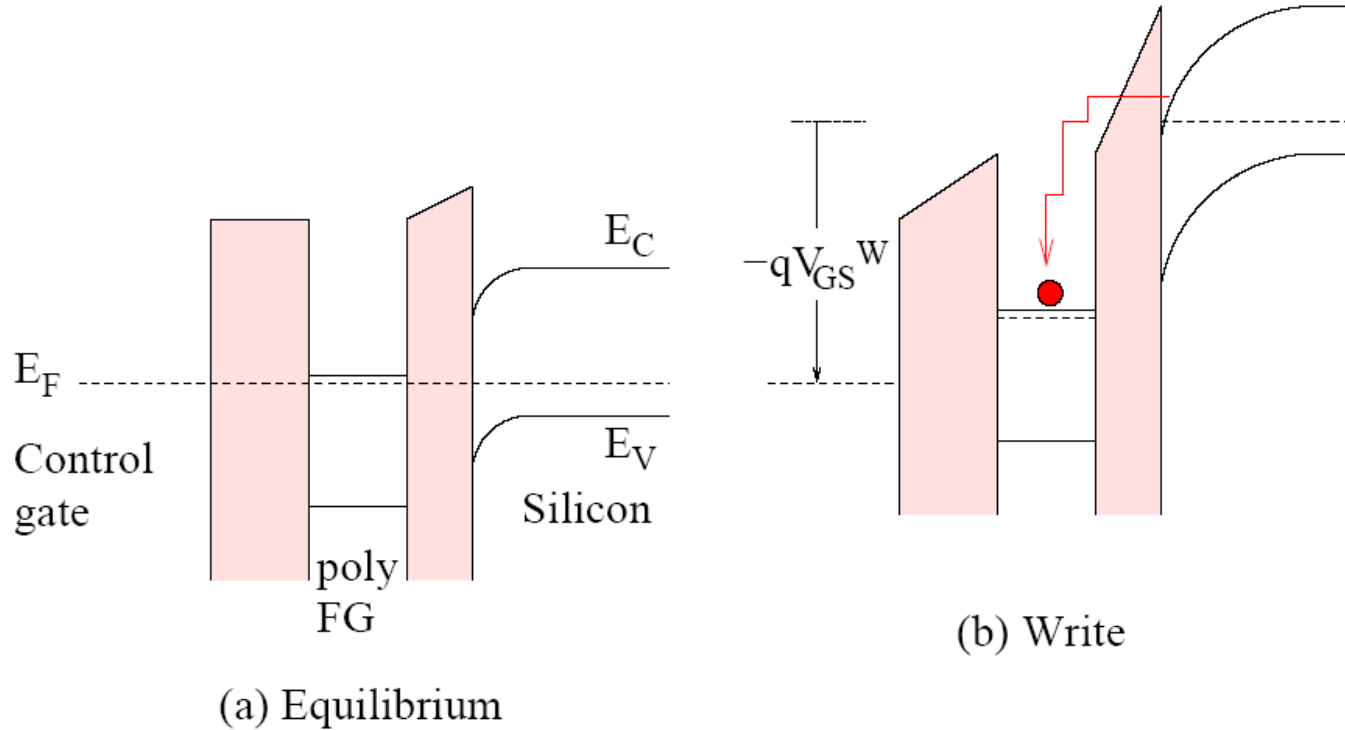
Enable word line.

Does the bit-line sense an  $I_D$  in (a) and/or (b)?

What is the difference in  $V_T$  in the two cases?

How is a ONE/ZERO interpreted?

Is the reading destructive?



$$T \approx \exp \left[ -\frac{2d}{\hbar} \sqrt{2m_2^*(U_2 - E)} \right]$$

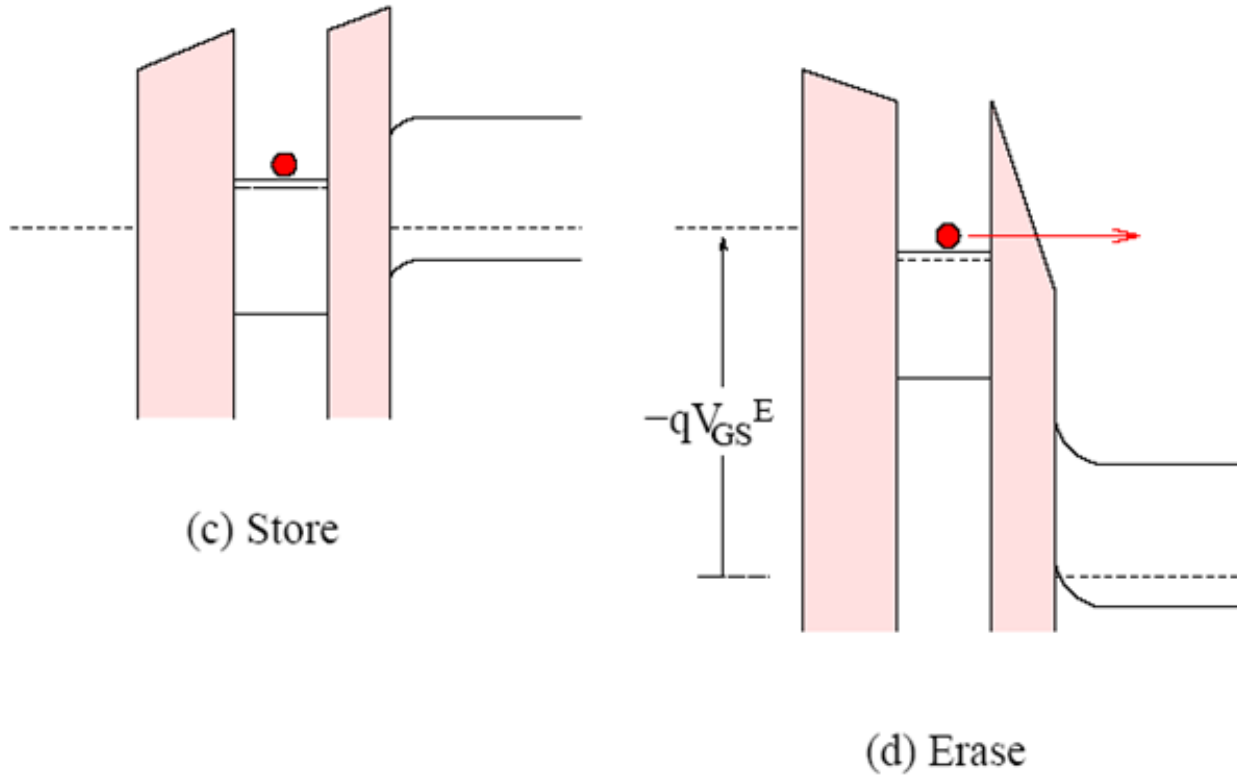
Where did this expression come from?

Both oxides are too thick for

Apply large  voltage. This enables FAT.

Electrons become trapped in the

## Storing, and Erasing a 0



What happens to the stored charge if the power fails?

What's the polarity of the erase voltage?

[http://www.toshiba.co.jp/about/press/2009\\_08/pr0401.htm](http://www.toshiba.co.jp/about/press/2009_08/pr0401.htm)

## Toshiba to Launch the World's First SDXC Memory Card

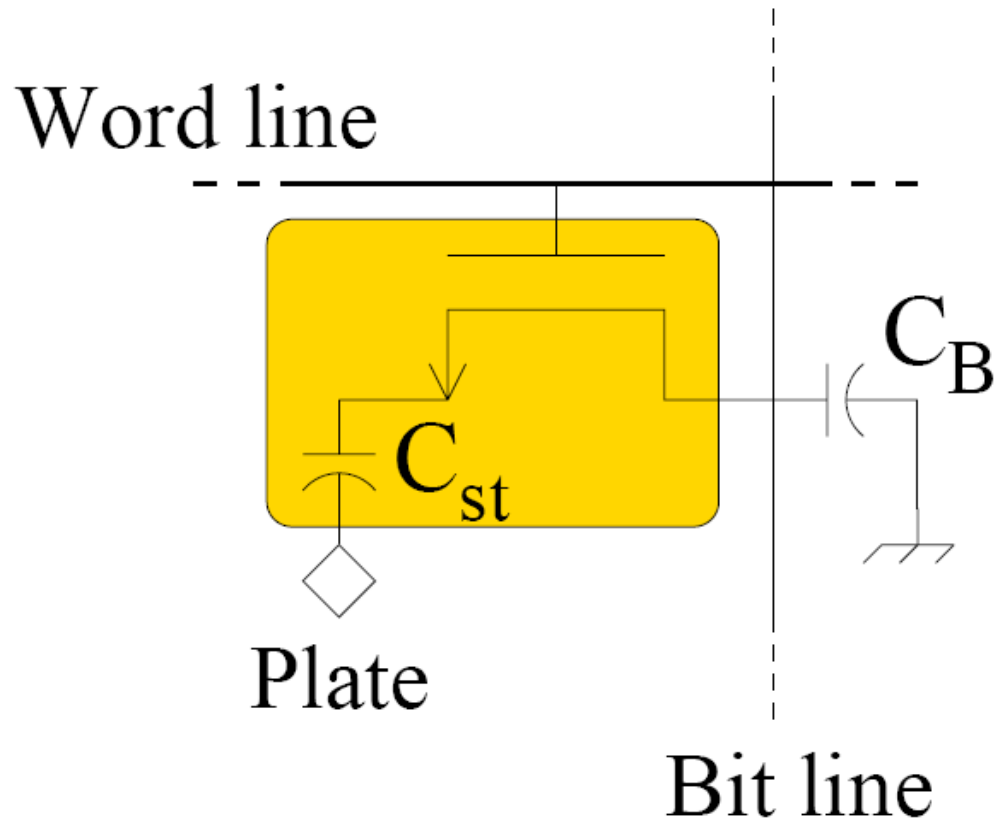
World's largest 64gigabyte (GB), with world's fastest transfer rate



How has TOSHIBA done this?



## DRAM



Where is the charge stored?

What is the function of the MOSFET?

How is the cell read?

What is the condition of the bit-line during a READ operation?

## Sec. 15.2

## Writing and Reading a ONE

WRITE:

Plate at  $V_{DD}/2$

Raise  $V_{Bit}$  to  $V_{DD}+V_T$

Enable word line.

What does  $V_S$  become?

What does  $V_{st}$  become?

READ:

Plate at  $V_{DD}/2$

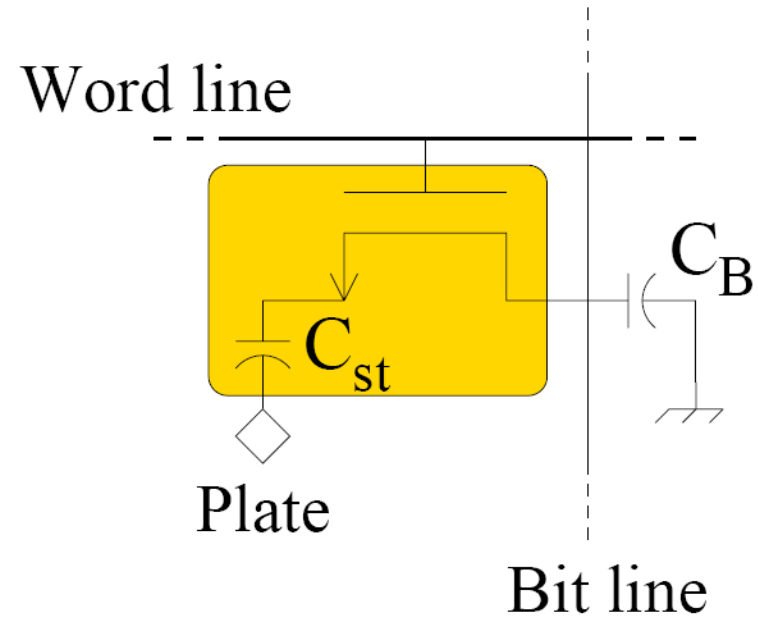
Pre-charge  $V_{Bit}$  to  $V_{DD}/2$

Float  $V_{Bit}$

Enable word line

Sense  $V_{Bit}$

What does  $V_{Bit}$  become?



## Sec. 15.2

# Writing and Reading a ZERO

WRITE:

Plate at  $V_{DD}/2$

What is  $V_{Bit}$  set to?

Enable word line.

What does  $V_S$  become?

What does  $V_{st}$  become?

READ:

Plate at  $V_{DD}/2$

Pre-charge  $V_{Bit}$  to  $V_{DD}/2$

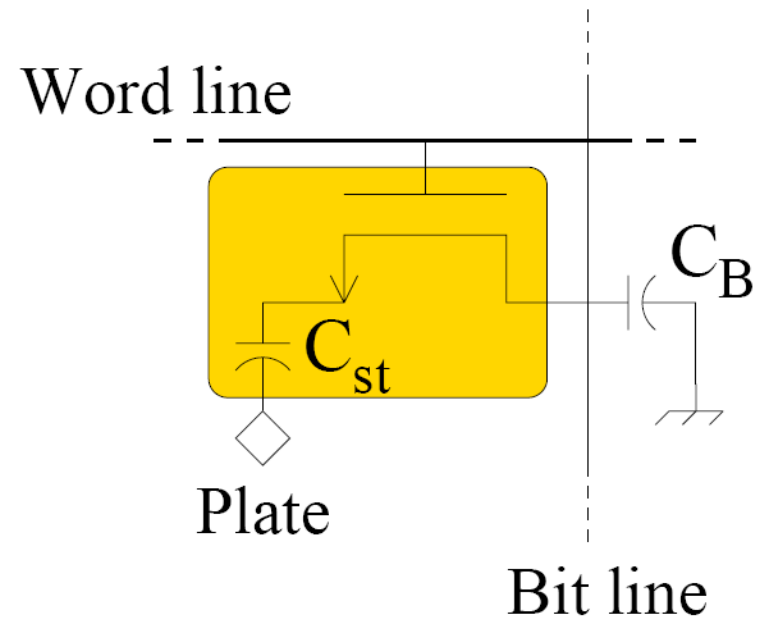
Float  $V_{Bit}$

Enable word line

Sense  $V_{Bit}$

What does  $V_{Bit}$  become?

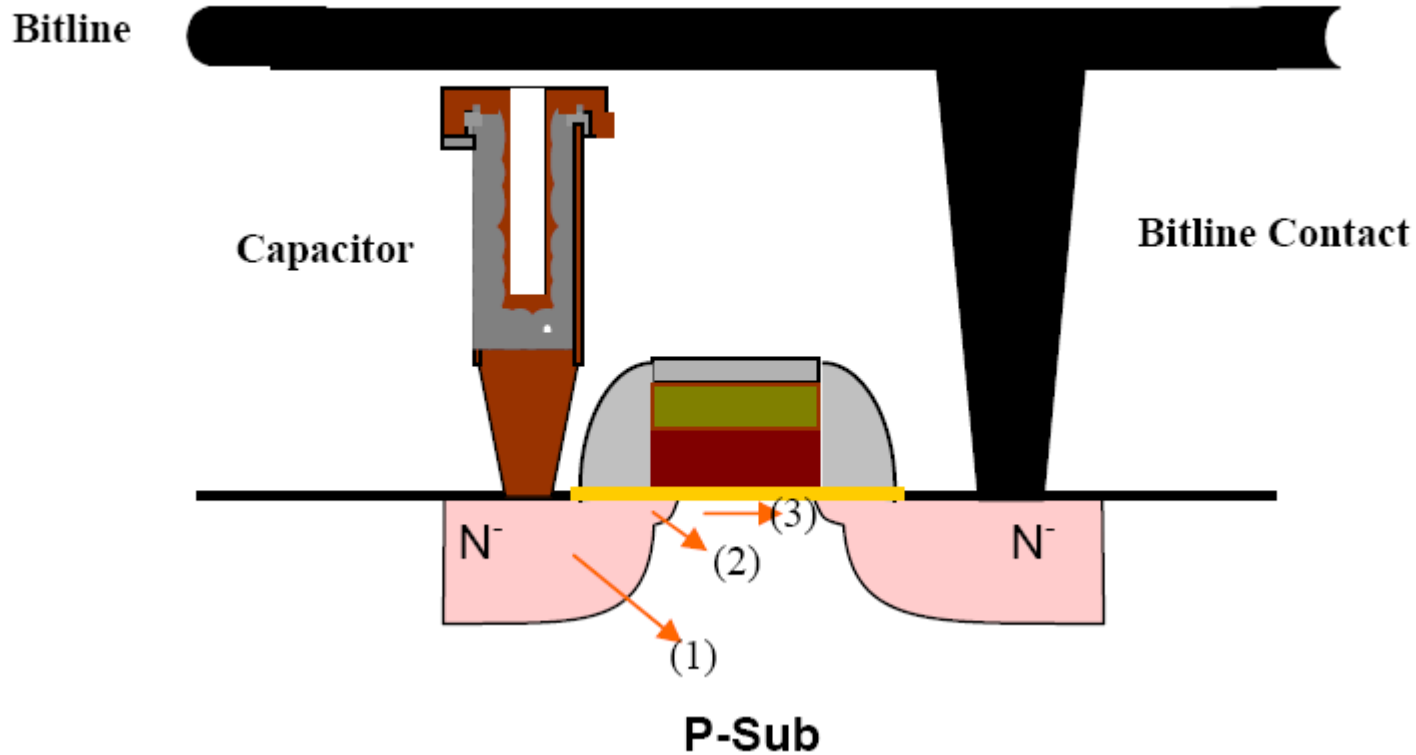
Does  $V_S$  change?



Why is this memory called "Dynamic"?

# Leakage currents

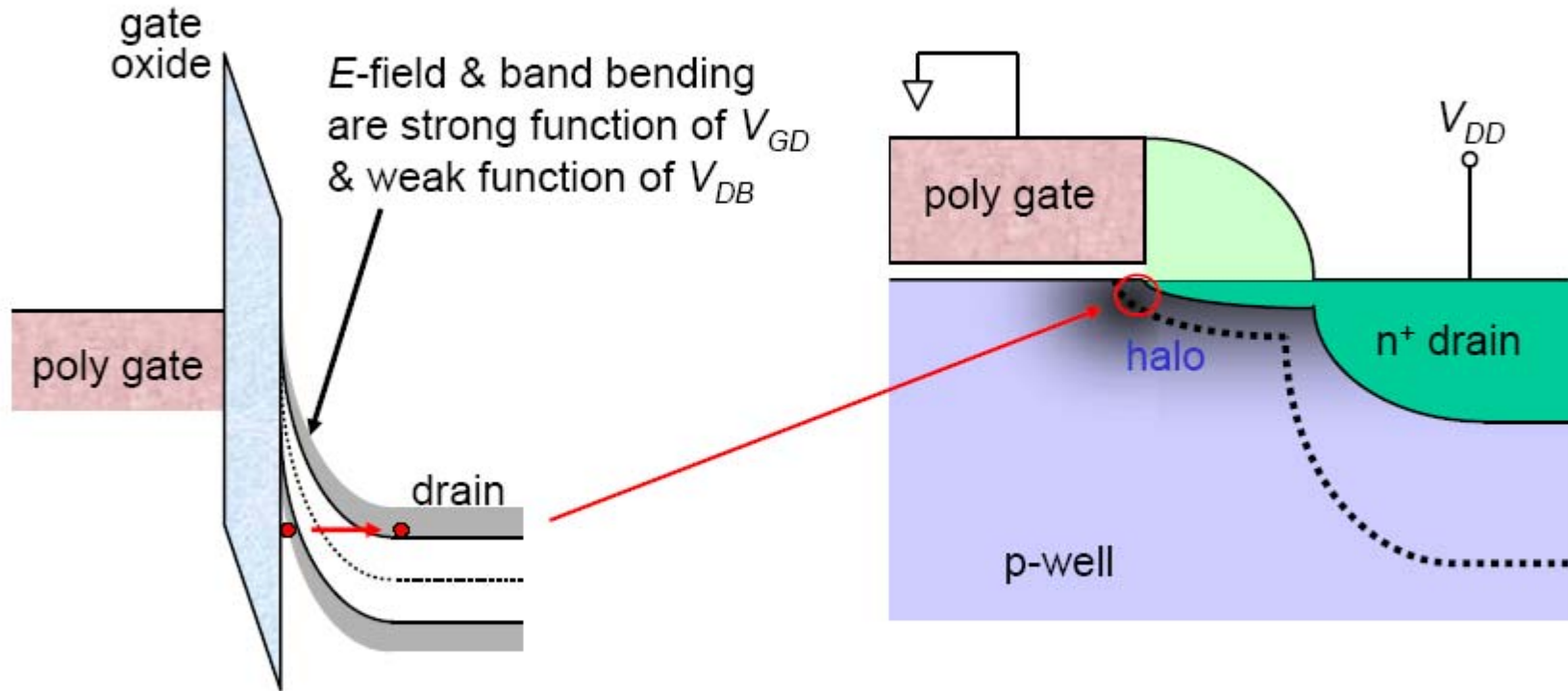
Another reason for frequent refreshing



- (1) Reverse Junction leakage current from the storage node
- (2) Gate Induced drain leakage (GIDL) current
- (3) Subthreshold leakage current of NMOS transistor

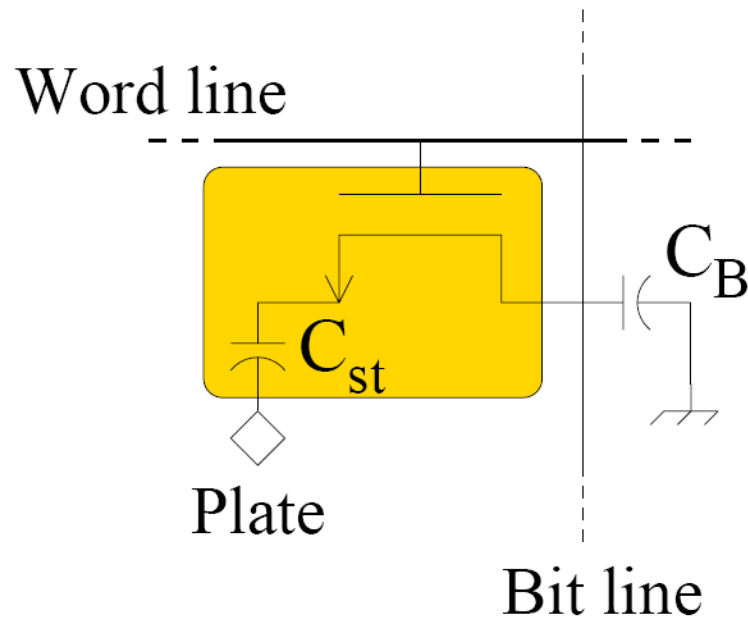
## Gate-Induced Drain Leakage (GIDL)

- Drain-to-substrate leakage due to band-to-band tunneling current in very high-field depletion region in drain overlap region



- Similar gate-induced source leakage (GISL) mechanism exists when source is raised above gate potential

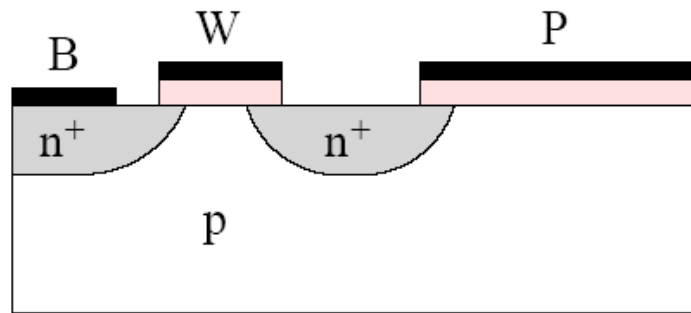
# Charge sharing



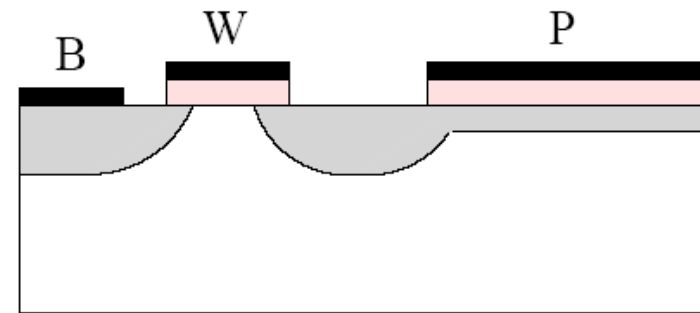
Basically, the DRAM works by altering the charge on the BIT line.

Therefore, is it required to make  $C_{st}$  as large or as small as possible?

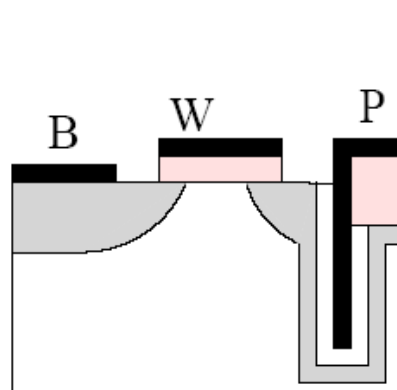
# DRAM-capacitor evolution



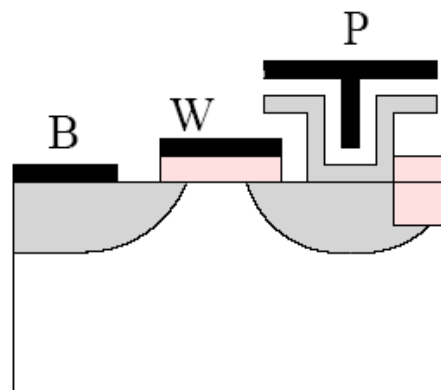
(a) MOS capacitor (4K)



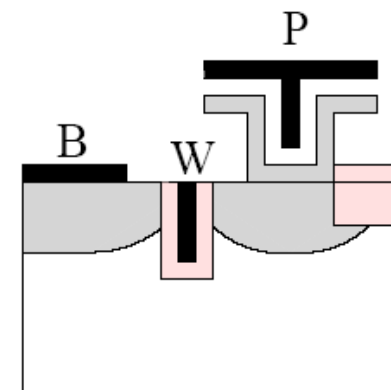
(b) Planar capacitor (64K – 1M)



(c) Trench capacitor  
(1M – 1G)



(d) Stacked capacitor  
(4M –)



(e) Buried word line  
(4G –)

# 480 reunion at the Hofbrauhaus

